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-- 8. (New) A semiconductor device comprising:  
a substrate;  
a circuit member provided on the substrate;  
a terminal provided on a back of the substrate and electrically connected to the circuit member through the substrate;  
a wall surrounding the circuit member; and  
a transparent plate with a light-shielding adhesive resin provided over the transparent plate's entire surface, said transparent plate adhered on the wall and over the circuit member to form an airtight cavity between the substrate and the transparent plate.

9 (New) The semiconductor device according to claim 8 wherein the circuit member comprises:

a conductive pattern disposed over the substrate; and  
a semiconductor chip disposed over the conductive pattern.

10. (New) The semiconductor device according to claim 8 wherein the substrate comprises insulating material.

11. (New) The semiconductor device according to claim 8, wherein the circuit member includes a fuse element.--

In the drawings:

Please substitute Figs. 9A and 9B with the corrected drawings enclosed herein.